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patternable material can be photopatternable or photosensitive material. Photopatternable materials include, for example, photosensitive polyimide, photosensitive polybenzoxazole, photoresists, photoresists based on novalac systems, and dry film resist materials. Photoresists based on novalac systems are particularly useful since they can be cured and crosslinked to provide improved mechanical integrity over other types of non-curable resists. Indirectly patternable materials, include, for example, spin-on glass materials, polyimide, polybenzoxazole, polygultarimide, benzocyclobutene, polymers such as polyethylene (PE), polystyrene (PSO), polypropylene (PP), or inorganic materials such as silicon dioxide, silicon nitride, and aluminum oxide.

In the claims:

Please amend claims 1, 2, 5, 7, 18-19, 22-24, 26-29, 32, 33, 36-38, 40-43, and 45-50 as follows:

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1. (Amended) A device comprising:
a substrate;
at least one active component formed on a top surface of the substrate;
a first laminate over the top surface of the substrate, encapsulating at least the active component; and
support posts in non-active regions of said device, providing support for said first laminate.
 2. (Amended) The device of claim 1 wherein the active component comprises an organic light emitting diode device.
 3. ~~The device of claim 2 wherein the substrate supports the active component.~~
 4. ~~The device of claim 3 wherein the substrate comprises a flexible substrate.~~

B3 5. (Amended) The device of claim 4 wherein the substrate comprises a substrate material selected from a group of materials consisting of polymer, glass, ceramic, or semiconductor material.

~~6. The device of claim 3 wherein the substrate comprises a transparent substrate.~~

B4 7. (Amended) The device of claim 6 wherein the substrate is selected from a group of materials consisting of polymer or glass.

~~8. The device of claim 3 wherein the substrate comprises a flexible transparent substrate.~~

~~9. The device of claim 8 wherein the substrate comprises a material selected from a polymer or glass.~~

~~10. The device of claim 1 wherein the substrate supports the active component.~~

~~11. The device of claim 10 wherein the substrate comprises a flexible substrate.~~

~~12. The device of claim 11 wherein the substrate material is selected from a group of materials consisting of polymer, glass, ceramic, or semiconductor material.~~

~~13. The device of claim 10 wherein the substrate comprises a transparent substrate.~~

~~14. The device of claim 13 wherein the substrate material is selected from a group of materials consisting of polymer or glass.~~

~~15. The device of claim 10 wherein the substrate comprises a flexible transparent substrate.~~

~~16. The device of claim 15 wherein the substrate comprises a material selected from a polymer or glass.~~

~~17. The device of claim 13 or 14 further comprises a second laminate on a bottom surface of the substrate, wherein the second laminate comprises a transparent laminate.~~

85 18. (Amended) The device of claim 17 wherein the first and second laminates comprise:

a laminate substrate; and

a sealant on a surface of the laminate substrate that contacts the device.

19. (Amended) The device of claim 18 wherein the laminate substrate comprises a material having a sufficient thermal stability to maintain mechanical integrity during the laminating process.

~~20. The device of claim 19 wherein the laminate substrate comprises a plastic material.~~

~~21. The device of claim 20 wherein the plastic laminate substrate is selected from poly (ethylene terephthalate), poly (butylene terephthalate), poly (ethylene naphthalate), polycarbonate, polyimides, polysulfones, poly (p-phenylene ether sulfone), polyethylene, polypropylene, poly(vinyl chloride), polystyrene, or poly (methyl methacrylate).~~

86 22. (Amended) The device of claim 21 wherein the sealant comprises an activation temperature which causes the sealant to flow to ensure sealing between the laminate substrate and the device.

23. (Amended) The device of claim 22 wherein the activation temperature is between 80°C and 140°C.

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24. (Amended) The device of claim 23 wherein the first and second laminates comprise a barrier layer, wherein the barrier layer inhibits the diffusion of air or moisture.

25. ~~The device of claim 24 wherein the barrier layer comprises a material selected from a group consisting of a metallic or a dielectric material.~~

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26. (Amended) The device of claim 25 wherein the metallic material comprises copper or aluminum and the dielectric material comprises silicon monoxide, silicon oxide, silicon dioxide, silicon nitride (Si_2N_4), or a metal oxide.

27. (Amended) The device of claim 26 wherein the sealant comprises an activation temperature which causes the sealant to flow to ensure sealing between the laminate substrate and the device.

28. (Amended) The device of claim 27 wherein the activation temperature is between 80°C and 140°C.

29. (Amended) The device of claim 18 wherein the first and second laminates comprise a barrier layer on the laminate, the barrier layer inhibits the diffusion of air or moisture.

~~30. The device of claim 29 wherein the barrier layer comprises a material selected from a group consisting of a metallic or a dielectric material.~~

31. The device of claim 10 further comprises a second laminate on a bottom surface of the substrate.

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32. (Amended) The device of claim 31 wherein said first and second laminates comprise:

- a laminate substrate; and
- a sealant on a surface of the laminate substrate that contacts the device.

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33. (Amended) The device of claim 32 wherein the laminate substrate comprises a material having a sufficient thermal stability to maintain mechanical integrity during the laminating process.

~~34. The device of claim 33 wherein the laminate substrate comprises a plastic material.~~

~~35. The device of claim 34 wherein the plastic laminate substrate is selected from poly (ethylene terephthalate), poly (butylene terephthalate), poly (ethylene naphthalate), polycarbonate, polyimides, polysulfones, poly (p-phenylene ether sulfone), polyethylene, polypropylene, poly (vinyl chloride), polystyrene, or poly(methyl methacrylate).~~

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36. (Amended) The device of claim 35 wherein the sealant comprises an activation temperature which causes the sealant to flow to ensure sealing between the laminate substrate and the device.

37. (Amended) The device of claim 36 wherein the activation temperature is between temperatures of 80°C and 140°C.

38. (Amended) The device of claim 37 wherein the first and second laminates comprise a barrier layer on the laminate, the barrier layer inhibits the diffusion of air or moisture.

~~39. The device of claim 38 wherein the barrier layer comprises a material selected from a group consisting of a metallic or a dielectric material.~~

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40. (Amended) The device of claim 39 wherein the metallic material comprises copper or aluminum and the dielectric material comprises silicon monoxide, silicon oxide, silicon dioxide, silicon nitride (Si₃N₄), or a metal oxide.

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41. (Amended) The device of claim 32 wherein the sealant comprises an activation temperature which causes the sealant to flow to ensure good sealing between the laminate substrate and the device.

42. (Amended) The device of claim 41 wherein the activation temperature is between temperatures of 80°C and 140°C.

43. (Amended) The device of claim 32 wherein the first and second laminates comprise a barrier layer on the laminate, the barrier layer inhibits the diffusion of air or moisture.

~~44. The device of claim 43 wherein the barrier layer comprises a material selected from a group consisting of a metallic or a dielectric material.~~

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45. (Amended) The device of claim 2 wherein the first laminate comprises:
a laminate substrate; and
a sealant on a surface of the laminate substrate that contacts the device.

46. (Amended) The device of claim 45 wherein the laminate substrate comprises a material having a sufficient thermal stability to maintain mechanical integrity during the laminating process.

47. (Amended) The device of claim 46 wherein the sealant comprises an activation temperature which causes the sealant to flow to ensure sealing between the laminate substrate and the device.

48. (Amended) The device of claim 47 wherein the first laminate comprises a barrier layer on the laminate, the barrier layer inhibits the diffusion of air or moisture.

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49. (Amended) The device of claim 45 wherein the sealant comprises an activation temperature which causes the sealant to flow to ensure sealing between the laminate and the device.

50. (Amended) The device of claim 45 wherein the first laminate comprises a barrier layer on the laminate, the barrier layer inhibits the diffusion of air or moisture. --

Please add claims 86-94.

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86. (New) The device of claim 1 wherein the support posts comprise directly or indirectly photopatternable material. ✓

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87. (New) The device of claim 86 wherein the photopatternable material is a directly photopatternable material selected from a group consisting of photosensitive polyimide, photosensitive polybenzoxalole, photoresists, photoresists based on novolac systems or dry film resist materials.

88. (New) The device of claim 86 wherein the indirectly photopatternable material is selected from the group consisting of spin-on glass, polyimide, polybenzoxazole, polyglutarimide, benzocyclobutene, polymers, polyethylene, polystyrene, polystyrene, polypropylene, silicon dioxide, silicon nitride or aluminum oxide.

89. (New) The device of claim 86 wherein the support posts comprise a multi-layer architecture having at least first and second support layers.

90. (New) The device of claim 87 wherein the support posts comprise a multi-layer architecture having at least first and second support layers.

91. (New) The device of claim 88 wherein the first support layer comprises a dielectric material to provide electrical isolation for the active component.

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92. (New) The device of claim 89 wherein the first support layer comprises a dielectric material to provide electrical isolation for the active component.

93. (New) The device of claim 89 wherein the first and second support layers comprise directly or indirectly photopatternable material.

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94. (New) The device of claim 90 wherein the first and second support layers comprise directly or indirectly photopatternable material.--
